

TSM60N750

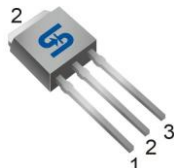
600V, 6A, 0.75Ω

N-Channel Power MOSFET

TO-252
(DPAK)



TO-251
(IPAK)



Pin Definition:

1. Gate
2. Drain
3. Source

Key Parameter Performance

Parameter	Value	Unit
V_{DS}	600	V
$R_{DS(on)}$ (max)	0.75	Ω
Q_g	10.8	nC

Features

- Super-Junction technology
- High performance due to small figure-of-merit
- High ruggedness performance
- High commutation performance

Application

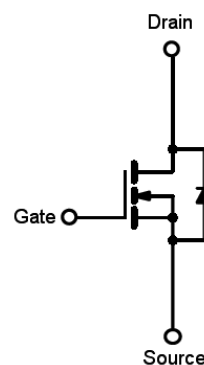
- Power Supply.
- Lighting

Ordering Information

Part No.	Package	Packing
TSM60N750CH C5G	TO-251	75pcs / Tube
TSM60N750CP ROG	TO-252	2.5kpcs / 13" Reel

Note: "G" denotes for Halogen- and Antimony-free as those which contain <900ppm bromine, <900ppm chlorine (<1500ppm total Br + Cl) and <1000ppm antimony compounds

Block Diagram



N-Channel MOSFET

Absolute Maximum Ratings ($T_A=25^{\circ}C$ unless otherwise noted)

Parameter	Symbol	Limit	Unit
		IPAK/DPAK	
Drain-Source Voltage	V_{DS}	600	V
Gate-Source Voltage	V_{GS}	±30	V
Continuous Drain Current ^(Note 1)	I_D	6	A
Pulsed Drain Current ^(Note 2)			
Total Power Dissipation @ $T_C=25^{\circ}C$	P_{DTOT}	62.5	W
Single Pulsed Avalanche Energy ^(Note 3)	E_{AS}	90	mJ
Single Pulsed Avalanche Current ^(Note 3)	I_{AS}	1.9	A
Operating Junction and Storage Temperature Range	T_J, T_{STG}	- 55 to +150	°C



Thermal Performance

Parameter	Symbol	Limit	Unit
		IPAK/DPAK	
Junction to Case Thermal Resistance	$R_{\theta JC}$	2	$^{\circ}\text{C/W}$
Junction to Ambient Thermal Resistance	$R_{\theta JA}$	62	$^{\circ}\text{C/W}$

Electrical Specifications ($T_J=25^{\circ}\text{C}$ unless otherwise noted)

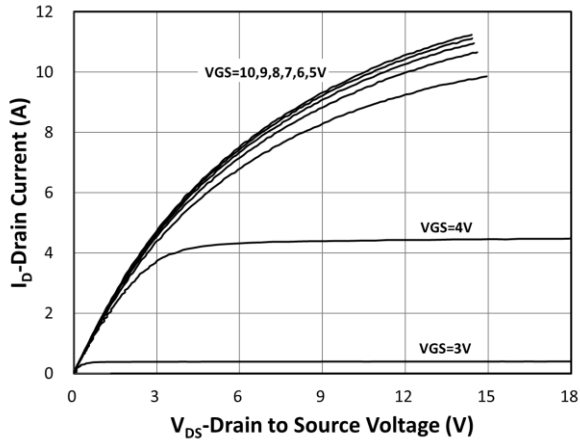
Parameter	Conditions	Symbol	Min	Typ	Max	Unit
Static (Note 4)						
Drain-Source Breakdown Voltage	$V_{GS} = 0\text{V}, I_D = 250\mu\text{A}$	BV_{DSS}	600	--	--	V
Gate Threshold Voltage	$V_{DS} = V_{GS}, I_D = 250\mu\text{A}$	$V_{GS(TH)}$	2	3	4	V
Gate Body Leakage	$V_{GS} = \pm 30\text{V}, V_{DS} = 0\text{V}$	I_{GSS}	--	--	± 100	nA
Zero Gate Voltage Drain Current	$V_{DS} = 600\text{V}, V_{GS} = 0\text{V}$	I_{DSS}	--	--	1	μA
Drain-Source On-State Resistance	$V_{GS} = 10\text{V}, I_D = 3\text{A}$	$R_{DS(ON)}$	--	0.53	0.75	Ω
Dynamic (Note 5)						
Total Gate Charge	$V_{DS} = 380\text{V}, I_D = 6\text{A},$ $V_{GS} = 10\text{V}$	Q_g	--	10.8	--	nC
Gate-Source Charge		Q_{gs}	--	2.7	--	
Gate-Drain Charge		Q_{gd}	--	3.7	--	
Input Capacitance	$V_{DS} = 100\text{V}, V_{GS} = 0\text{V},$ $f = 1.0\text{MHz}$	C_{iss}	--	554	--	pF
Output Capacitance		C_{oss}	--	46	--	
Gate Resistance	$f=1\text{MHz}, \text{open drain}$	R_g	--	2.7	--	Ω
Switching (Note 6)						
Turn-On Delay Time	$V_{DD} = 380\text{V},$ $R_{GEN} = 25\Omega,$ $I_D = 6\text{A}, V_{GS} = 10\text{V},$	$t_{d(on)}$	--	17.3	--	ns
Turn-On Rise Time		t_r	--	22	--	
Turn-Off Delay Time		$t_{d(off)}$	--	28	--	
Turn-Off Fall Time		t_f	--	22	--	
Source-Drain Diode (Note 4)						
Forward On Voltage	$I_S=6\text{A}, V_{GS}=0\text{V}$	V_{SD}	--	--	1.4	V
Reverse Recovery Time	$V_R=200\text{V}, I_S=3\text{A}$ $di_f/dt=100\text{A}/\mu\text{s}$	t_{rr}	--	182	--	ns
Reverse Recovery Charge		Q_{rr}	--	1.3	--	μC

Notes:

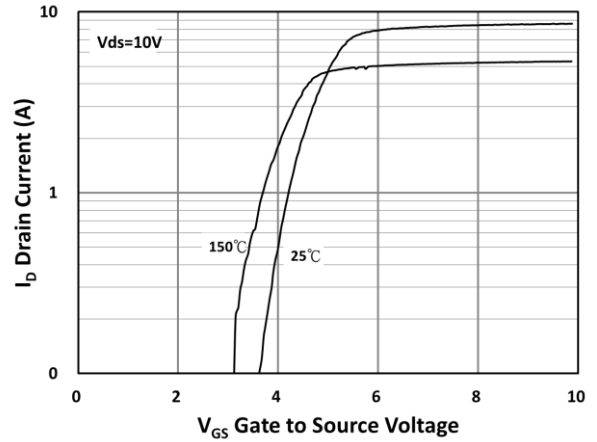
1. Current limited by package
2. Pulse width limited by the maximum junction temperature
3. $L=50\text{mH}, I_{AS}=1.9\text{A}, V_{DD}=50\text{V}, R_G=25\Omega$, Starting $T_J=25^{\circ}\text{C}$
4. Pulse test: $PW \leq 300\mu\text{s}$, duty cycle $\leq 2\%$
5. For DESIGN AID ONLY, not subject to production testing.
6. Switching time is essentially independent of operating temperature.

Electrical Characteristics Curves

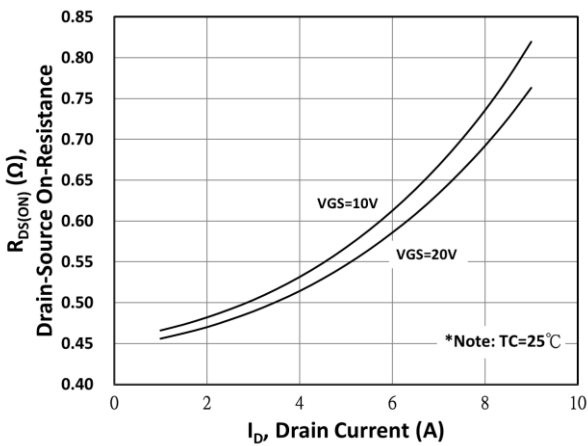
Output Characteristics



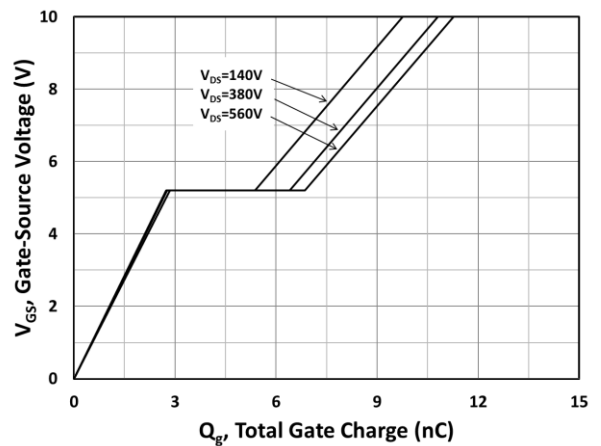
Transfer Characteristics



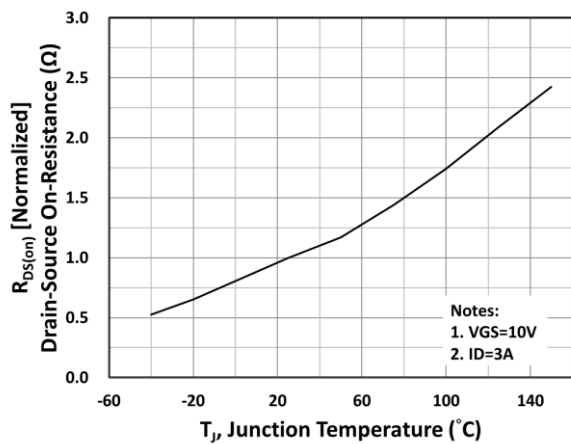
On-Resistance vs. Drain Current



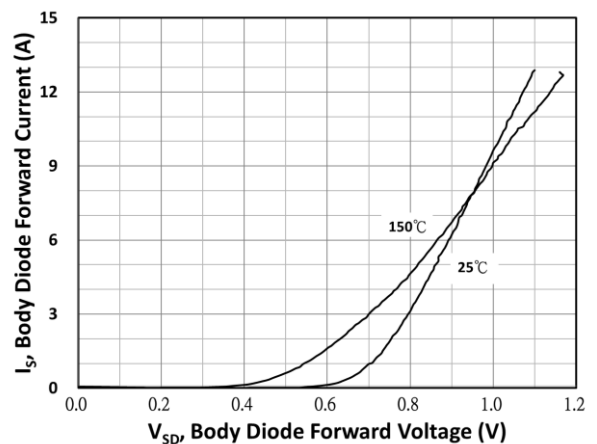
Gate-Source Voltage vs. Gate Charge



On-Resistance vs. Junction Temperature

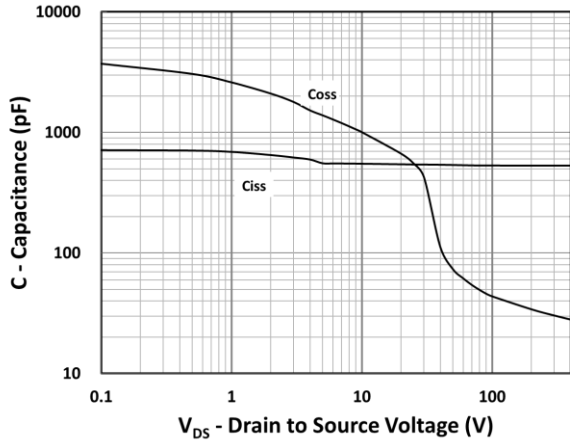


Source-Drain Diode Forward Current vs. Voltage

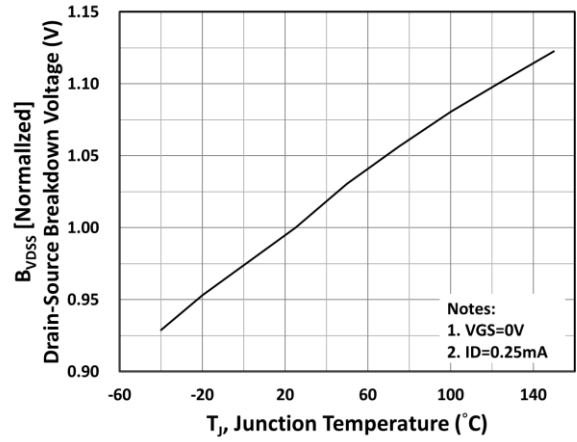


Electrical Characteristics Curves

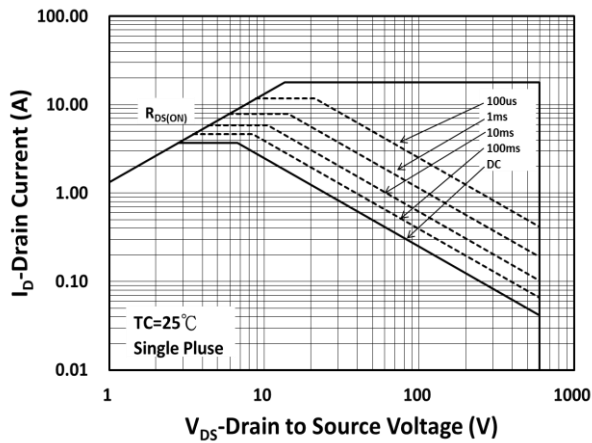
Capacitance vs. Drain-Source Voltage



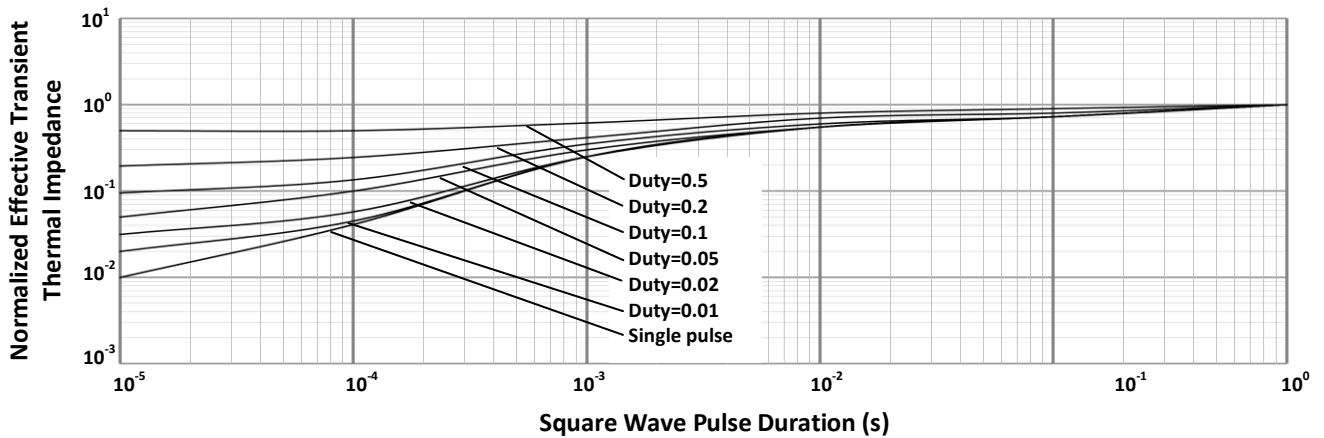
BV_{DSS} vs. Junction Temperature



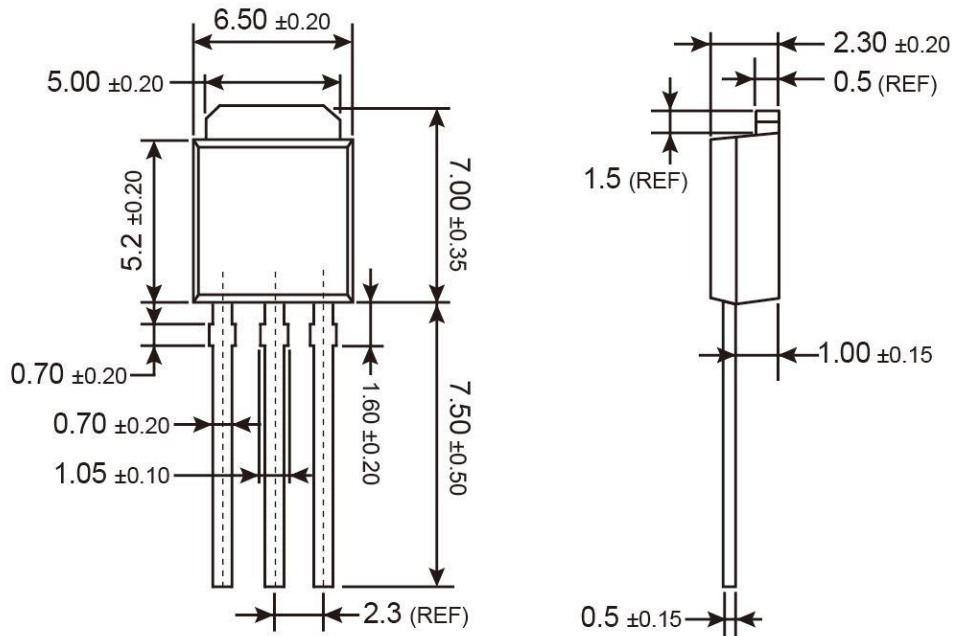
Maximum Safe Operating Area (DPAK/IPAK)



Normalized Thermal Transient Impedance, Junction-to-Case (DPAK/IPAK)

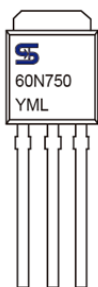


TO-251 (IPAK) Mechanical Drawing



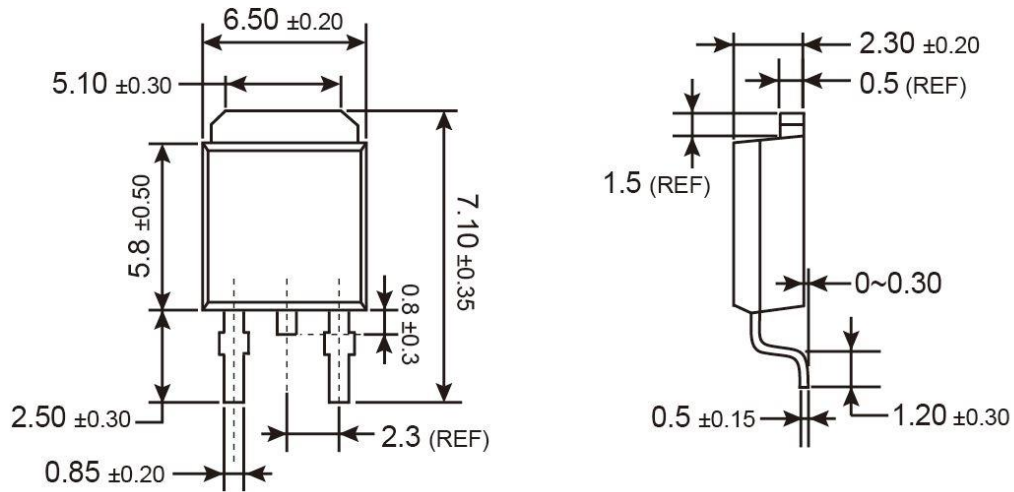
Unit: Millimeters

Marking Diagram



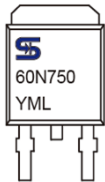
- Y** = Year Code
- M** = Month Code for Halogen Free Product
(**O**=Jan, **P**=Feb, **Q**=Mar, **R**=Apr, **S**=May, **T**=Jun, **U**=Jul, **V**=Aug, **W**=Sep, **X**=Oct, **Y**=Nov, **Z**=Dec)
- L** = Lot Code

TO-252 (DPAK) Mechanical Drawing



Unit: Millimeters

Marking Diagram



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